



Spec No. :DS70-2001-012 Effective Date: 06/20/2017

Revision: O

**LITE-ON DCC** 

RELEASE

BNS-OD-FC001/A4



### 1. DESCRIPTION

#### 1.1 Features

- Current transfer ratio (CTR : MIN. 50% at  $I_F = 5mA$ ,  $V_{CE} = 5V$ )
- High input-output isolation voltage (Viso = 3,750Vrms)
- High collector-emitter voltage ( $V_{CEO} = 35V$ )
- SOP-4 package
- Mini-flat package: 2.0mm profile: LTV-357T series
- Safety approval

UL 1577

VDE DIN EN60747-5-5 (VDE 0884-5),

CSA CA5A

CQC GB4943.1-2011/ GB8898-2011

FIMKO/DEMKO/SEMKO/NEMKO

- RoHS Compliance
  - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- ESD pass HBM 8000V/ MM2000V/ CDM2000V
- MSL class1

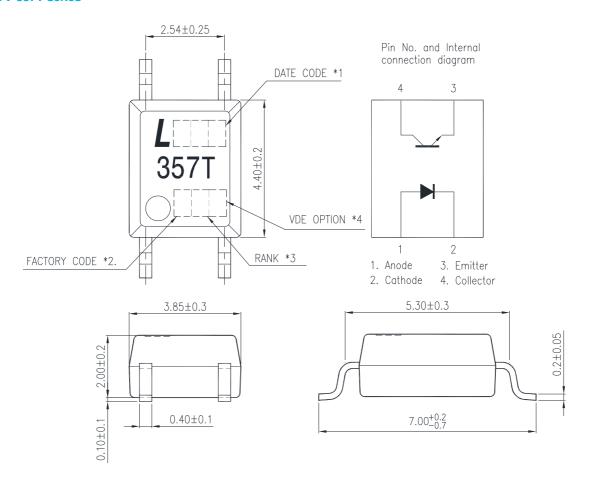
### 1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers
- System appliance, measuring instruments



### 2. PACKAGE DIMENSIONS

#### 2.1 LTV-357T series



### Notes:

- 1-digit year code, Example: 2010 = A
   2-digit work week ranging from '01' to '53'
- 2. Factory identification mark shall be marked (W: China -CZ, X: China -TJ)
- 3. Rank shall be or shall not be marked.
- 4. "●" indicates halogen free option.
- 5. "4"or"V" for VDE option.

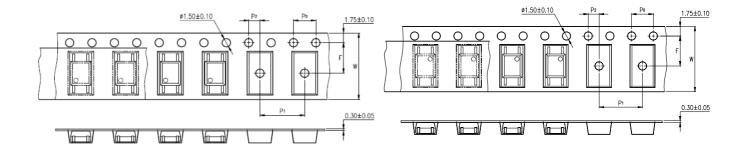
<sup>\*</sup>All dimensions in millimeters.



### 3. TAPING DIMENSIONS

### 3.1 LTV-357T-TP

### 3.2 LTV-357T



Description	Symbol	Dimension in mm (inch)
Tape wide	W	12±0.3 (0.472)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.157)
Distance of compartment	F	5.5±0.1 (0.217)
	P <sub>2</sub>	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	8±0.1 (0.315)

### 3.3 Quantities Per Reel

Package Type	LTV-357T series
Quantities (pcs)	3000



### 4. RATING AND CHARACTERISTICS

### 4.1 Absolute Maximum Ratings at Ta=25℃

	Parameter	Symbol	Rating	Unit
	Forward Current	l <sub>F</sub>	50	mA
lanut	Reverse Voltage	$V_{R}$	6	V
Input	Power Dissipation	Р	70	mW
	Junction Temperature		125	°C
	Collector - Emitter Voltage	$V_{\text{CEO}}$	35	V
	Emitter - Collector Voltage	$V_{\text{ECO}}$	6	V
Output	Collector Current	Ic	50	mA
	Collector Power Dissipation		150	mW
	Junction Temperature	TJ	125	°C
	Total Power Dissipation	P <sub>tot</sub>	170	mW
1.	Isolation Voltage	$V_{\rm iso}$	3750	$V_{rms}$
	Operating Temperature	$T_{opr}$	-55 ~ +110	°C
	Storage Temperature	$T_{stg}$	-55 ~ +150	°C
2.	Soldering Temperature	T <sub>sol</sub>	260	°C

### 1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.

### 2. For 10 Seconds



### 4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25℃

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Input	Forward Voltage	$V_{F}$	_	1.2	1.4	V	I <sub>F</sub> =20mA
	Reverse Current	I <sub>R</sub>	_	_	10	μΑ	V <sub>R</sub> =4V
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
Output	Collector Dark Current	I <sub>CEO</sub>	_	_	100	nA	V <sub>CE</sub> =20V, I <sub>F</sub> =0
	Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	35	_	_	V	I <sub>C</sub> =0.1mA, I <sub>F</sub> =0
	Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	6	_	—	V	I <sub>E</sub> =10μΑ, I <sub>F</sub> =0
TRANSFER CHARACTERISTICS	Collector Current	Ic	2.5	_	30	mA	I <sub>F</sub> =5mA
	Current Transfer Ratio	CTR	50	_	600	%	V <sub>CE</sub> =5V
	Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	_	0.2	V	I <sub>F</sub> =20mA I <sub>C</sub> =1mA
	Isolation Resistance	R <sub>iso</sub>	5×10 <sup>10</sup>	1×10 <sup>11</sup>	_	Ω	DC500V, 40 ~ 60% R.H.
	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Response Time (Rise)	tr	_	4	18	μs	V <sub>CE</sub> =2V,
	Response Time (Fall)	tf	_	3	18	μs	$I_C$ =2mA $R_L$ =100 $\Omega$ ,

1. CTR = 
$$\frac{I_C}{I_F} \times 100\%$$



### 5. RANK TABLE OF CURRENT TRANSFER RATIO (CTR)

CTR Rank	Min	Max	Condition
А	80	160	
В	130	260	
С	200	400	I <sub>F</sub> =5mA, V <sub>CE</sub> =5V, Ta=25°C
D	300	600	17-311A, VCE-3V, 14-23 C
Е	50	150	
A or B or C or D or No mark	50	600	



### 6. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

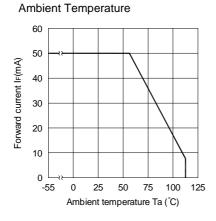


Fig.2 Collector Power Dissipation vs.
Ambient Temperature

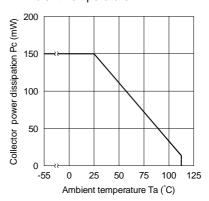


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

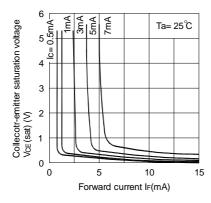


Fig.4 Forward Current vs. Forward Voltage

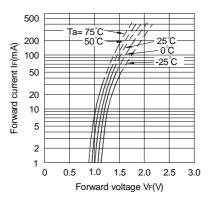


Fig.5 Current Transfer Ratio vs.
Forward Current

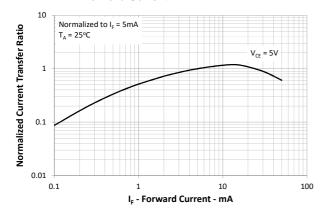


Fig.6 Collector Current vs.

Collector-emitter Voltage

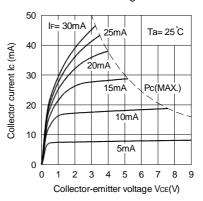




Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

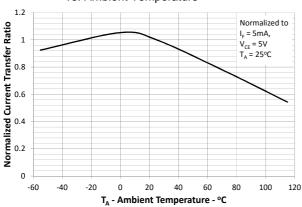


Fig.9 Collector Dark Current vs.
Ambient Temperature

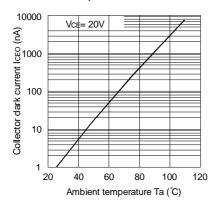


Fig.11 Frequency Response

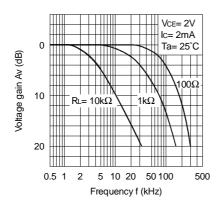


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

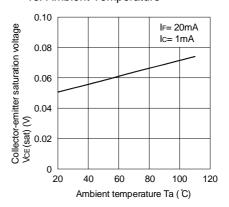
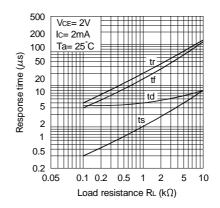
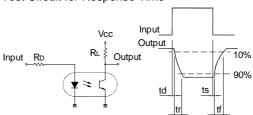


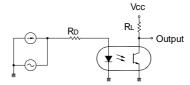
Fig.10 Response Time vs. Load Resistance



Test Circuit for Response Time



Test Circuit for Frequency Response



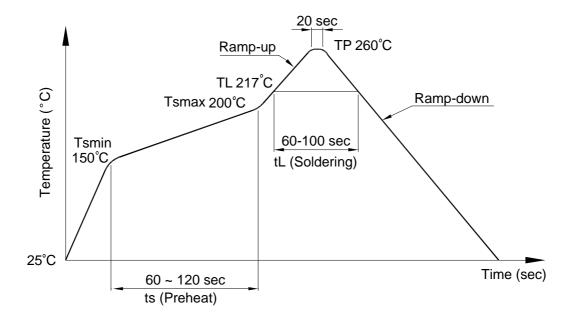


### 7. TEMPERATURE PROFILE OF SOLDERING

### 7.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions	
Preheat		
- Temperature Min (T <sub>Smin</sub> )	150°C	
- Temperature Max (T <sub>Smax</sub> )	200°C	
- Time (min to max) (ts)	90±30 sec	
Soldering zone		
- Temperature (T <sub>L</sub> )	217°C	
- Time (t∟)	60 ~ 100 sec	
Peak Temperature (T <sub>P</sub> )	260°C	
Ramp-up rate	3°C / sec max.	
Ramp-down rate	3~6°C / sec	





### 7.2 Wave soldering (JEDEC22A111 compliant)

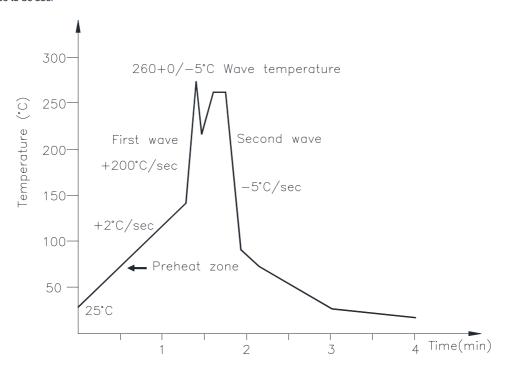
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



### 7.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

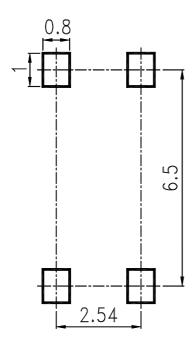
Temperature: 380+0/-5°C

Time: 3 sec max.



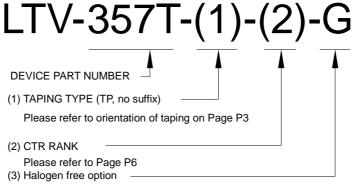
### 8. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm

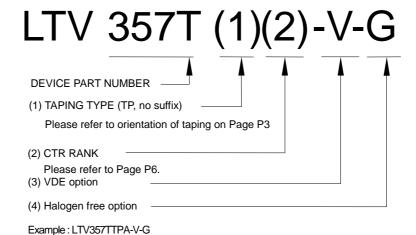




### 9. NAMING RULE



Example: LTV-357T-TP-A-G



### **10. NOTES**

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.